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(12) **United States Design Patent** (10) **Patent No.:** **US D772,823 S**
Lindeman (45) **Date of Patent:** **** Nov. 29, 2016**

(54) **HEAT SINK MODULE**

(71) Applicant: **EBULLIENT, LLC**, Madison, WI (US)

(72) Inventor: **Brett A. Lindeman**, Madison, WI (US)

(73) Assignee: **Ebullient, Inc.**, Madison, WI (US)

(**) Term: **15 Years**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**

USPC D13/179, 182; D15/199
CPC . H01L 23/473; H01L 23/4735; H01L 23/46;
H01L 23/467; H01L 23/4006; H01L 23/427;
F28D 15/00; F28D 15/02; F28D 15/0275;
F28F 31/02; G06F 1/20; G06F 2200/201
See application file for complete search history.

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Primary Examiner — Jennifer Rivard

Assistant Examiner — April Rivas

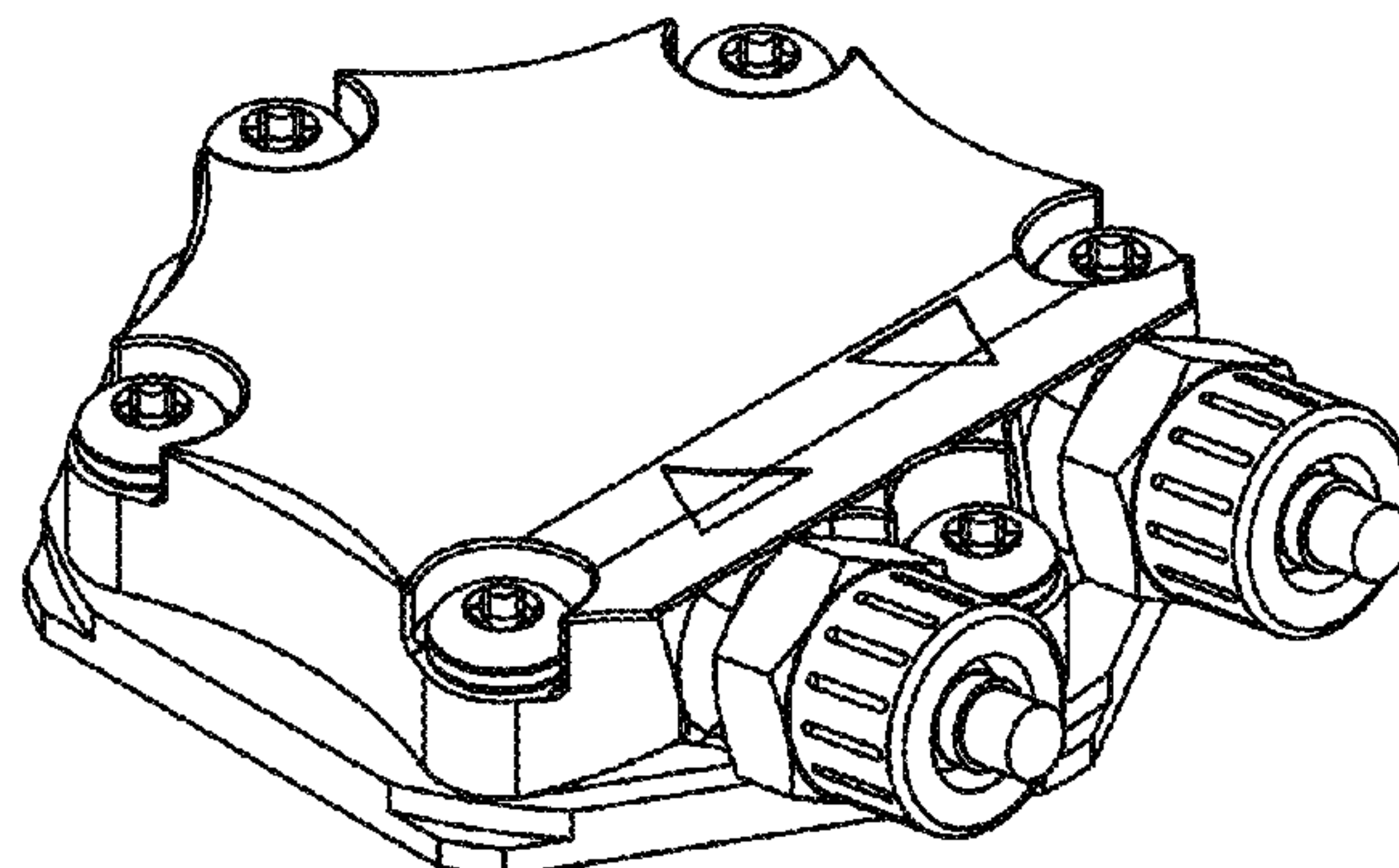
(57) **CLAIM**

The ornamental design for a heat sink module, as shown and described.

DESCRIPTION

FIG. 1 is top perspective view of a heat sink module;
FIG. 2 is a bottom perspective view of the heat sink module of FIG. 1;
FIG. 3 is a top view of the heat sink module of FIG. 1;
FIG. 4 is a bottom view of the heat sink module of FIG. 1;
FIG. 5 is a front view of the heat sink module of FIG. 1;
FIG. 6 is a rear view of the heat sink module of FIG. 1;
FIG. 7 is a left side view of the heat sink module of FIG. 1;
and,
FIG. 8 is a right side view of the heat sink module of FIG. 1.

1 Claim, 4 Drawing Sheets



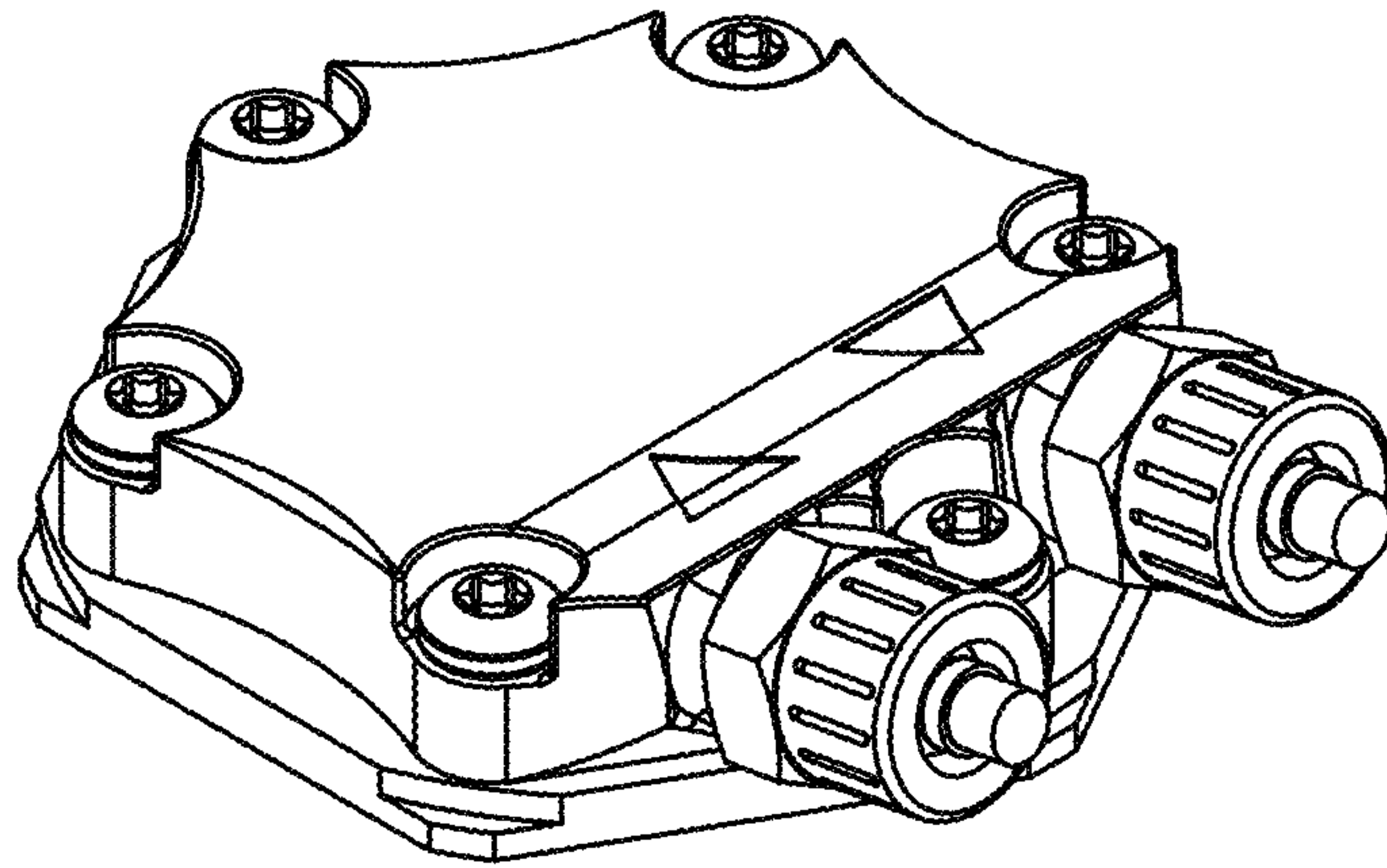


FIG. 1

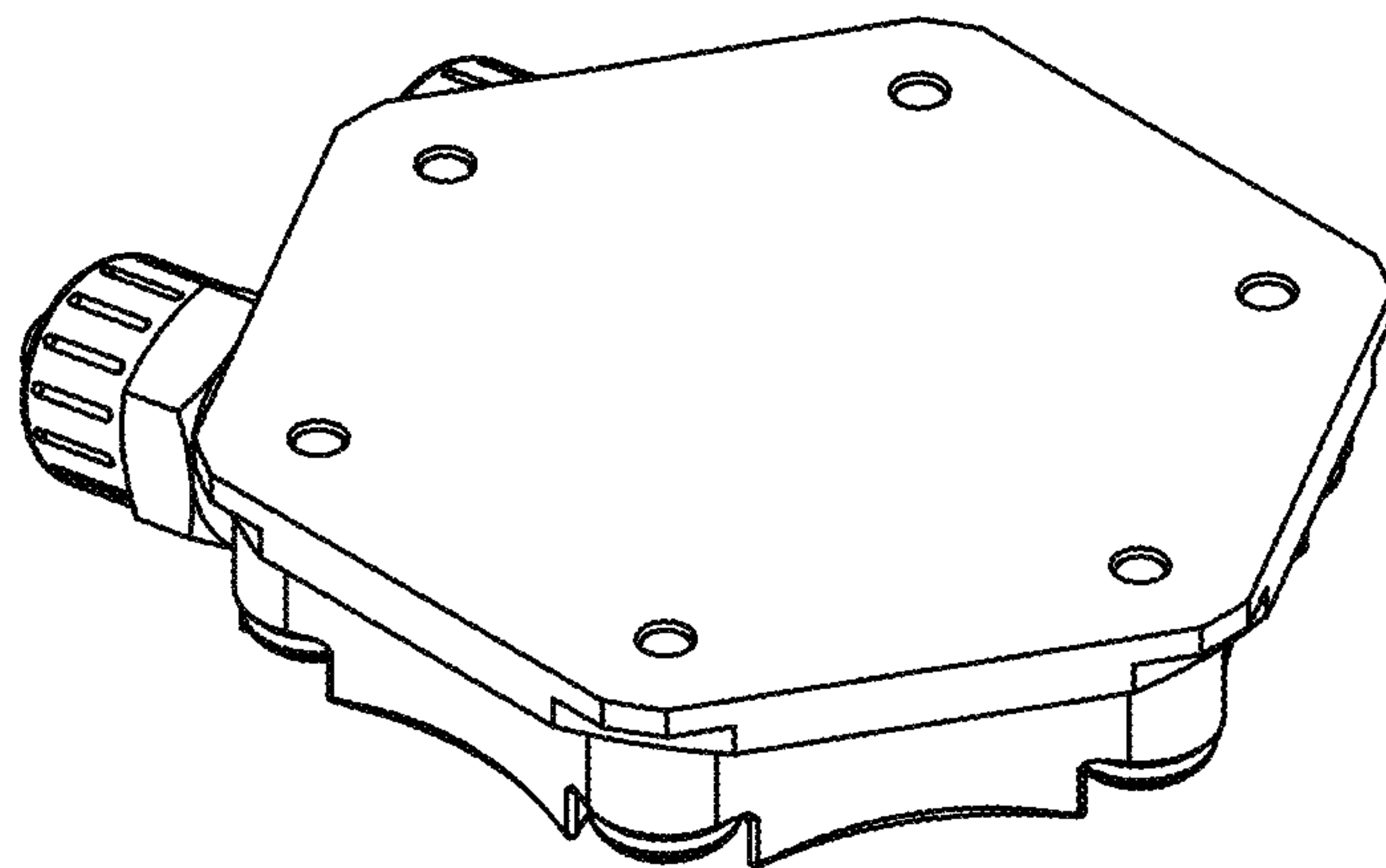


FIG. 2

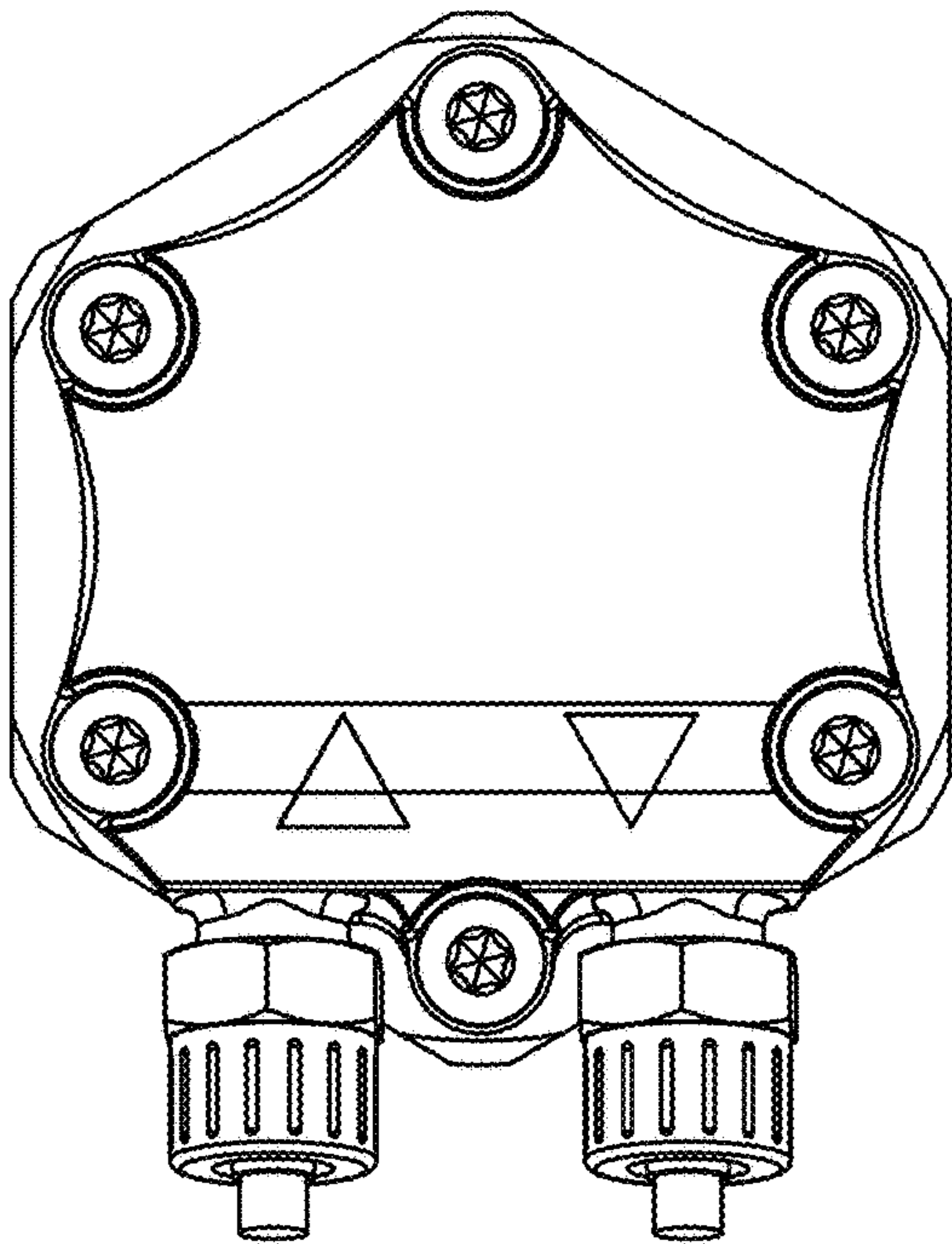


FIG. 3

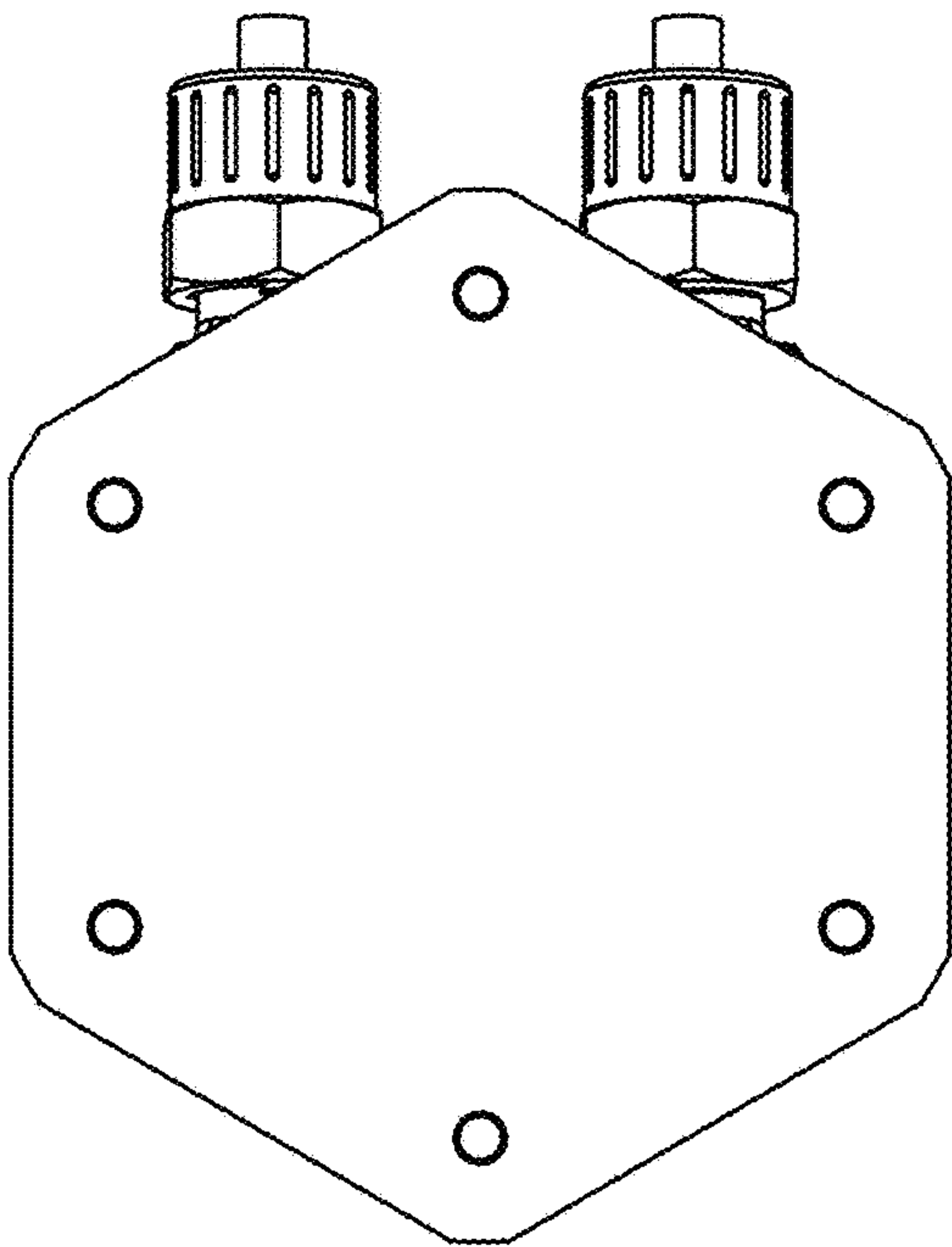


FIG. 4

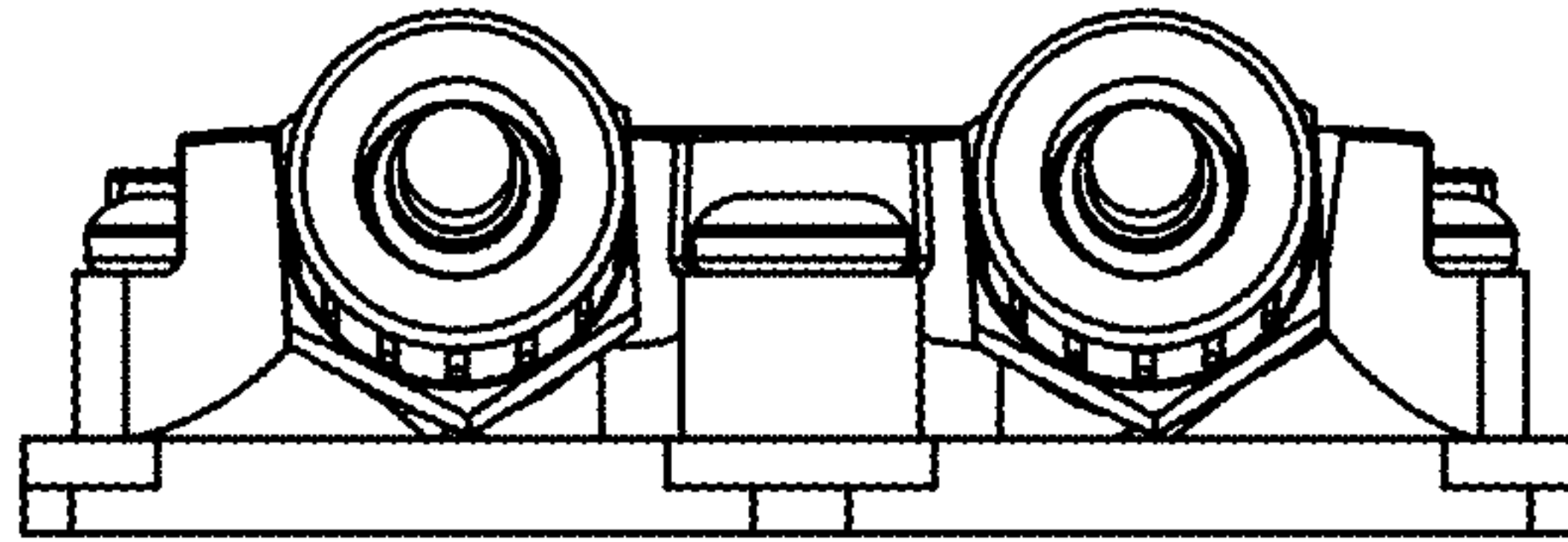


FIG. 5

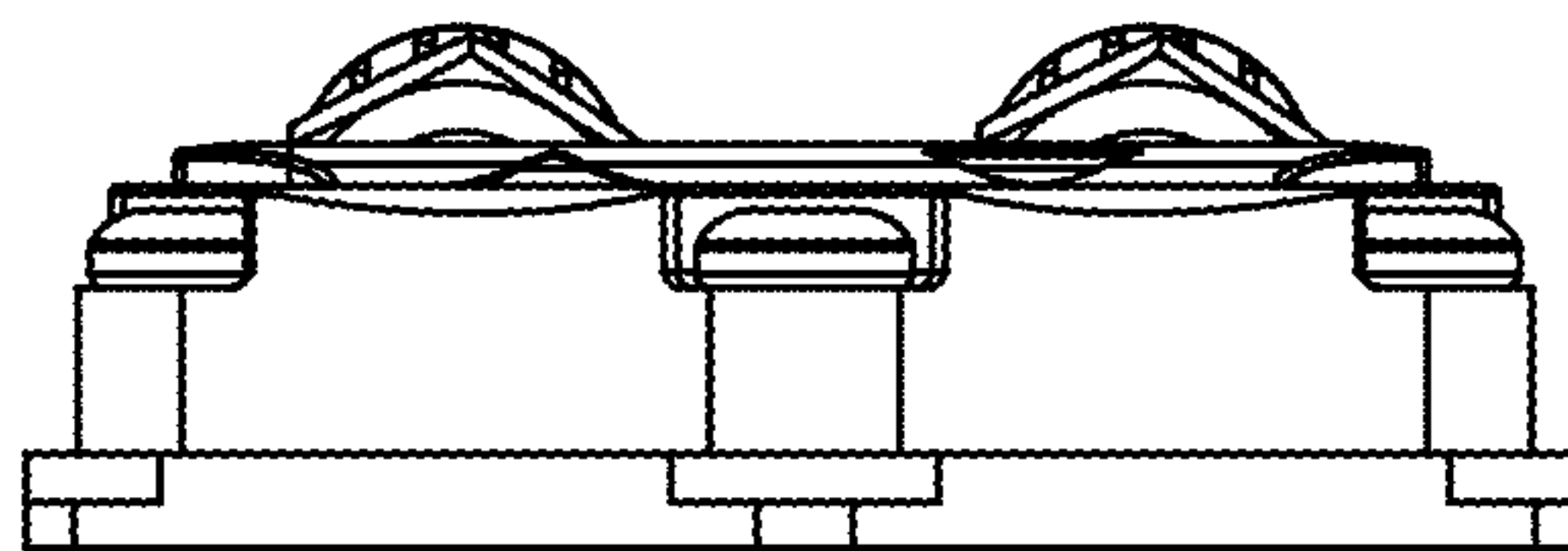


FIG. 6

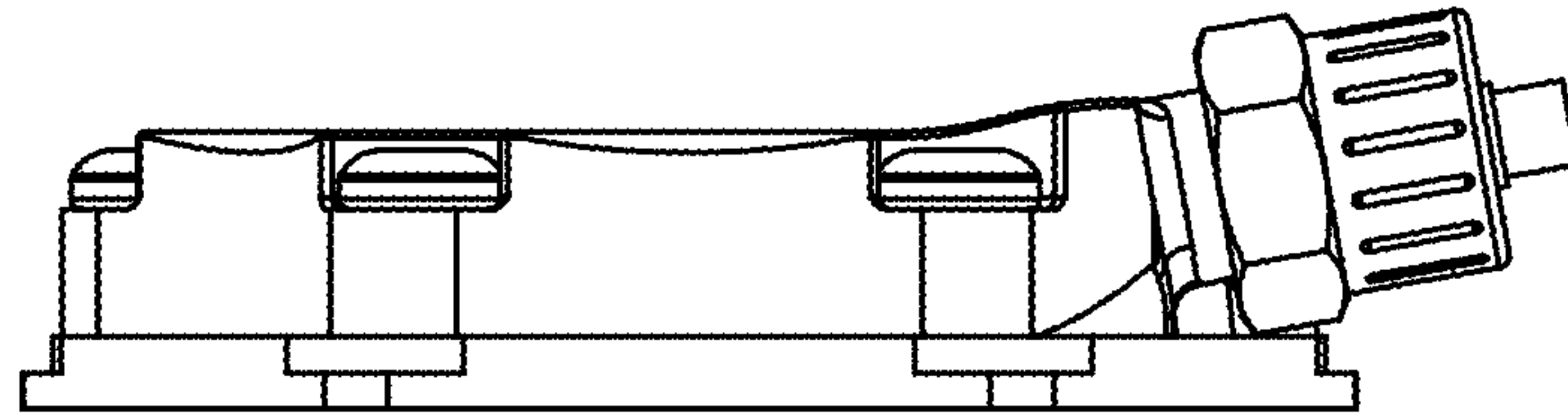


FIG. 7

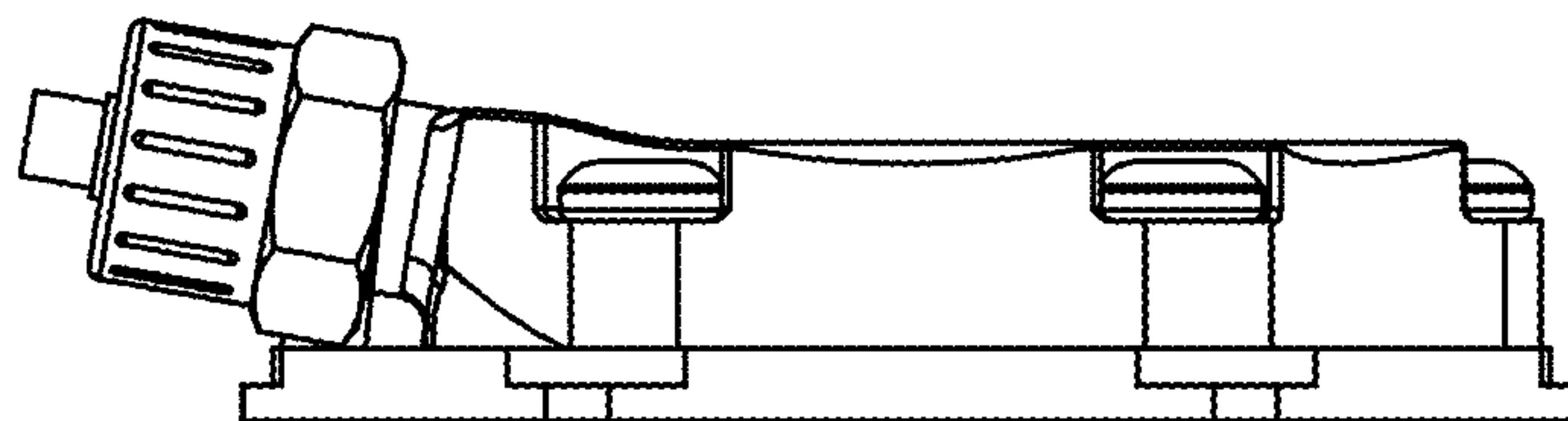


FIG. 8